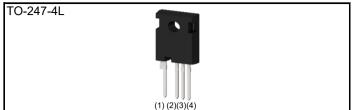


N-channel SiC power MOSFET

V_{DSS}	1200V
$R_{DS(on)}(Typ.)$	80mΩ
I _D *1	31A
P_D	165W

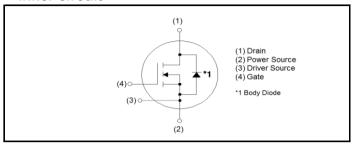
Outline



Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating; RoHS compliant

•Inner circuit



Please note Driver Source and Power Source are not exchangeable. Their exchange might lead to malfunction.

Application

- Solar inverters
- DC/DC converters
- · Switch mode power supplies
- · Induction heating
- Motor drives

Packaging specifications

	Packing	Tube
	Reel size (mm)	-
Type	Tape width (mm)	-
Туре	Basic ordering unit (pcs)	30
	Taping code	C14
	Marking	SCT3080KR

● Absolute maximum ratings (T_a = 25°C)

Parameter		Symbol	Value	Unit
Drain - Source Voltage		V_{DSS}	1200	V
Continuous Drain surrent	T _c = 25°C	I _D *1	31	Α
Continuous Drain current	T _c = 100°C	I _D ^{*1}	22	Α
Pulsed Drain current		I _{D,pulse} *2	77	Α
Gate - Source voltage (DC)		V_{GSS}	-4 to +22	V
Gate - Source surge voltage (t _{surge} < 300ns)		V _{GSS_surge} *3	-4 to +26	V
Recommended drive voltage		$V_{GS_op}^{*4}$	0 / +18	V
Junction temperature		T _j	175	°C
Range of storage temperature		T _{stg}	-55 to +175	°C

●Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
	Symbol	Conditions	Min.	Тур.	Max.	Unit
		$V_{GS} = 0V$, $I_D = 1mA$				
Drain - Source breakdown voltage	V _{(BR)DSS}	T _j = 25°C	1200	-	-	V
voltago		T _j = -55°C	1200	-	-	
		$V_{GS} = 0V, V_{DS} = 1200V$				
Zero Gate voltage Drain current	I _{DSS}	T _j = 25°C	-	1	10	μΑ
Drain sairein		T _j = 150°C	-	2	-	
Gate - Source leakage current	I _{GSS+}	$V_{GS} = +22V, V_{DS} = 0V$	-	-	100	nA
Gate - Source leakage current	I _{GSS-}	$V_{GS} = -4V$, $V_{DS} = 0V$	-	-	-100	nA
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V, I_{D} = 5mA$	2.7	-	5.6	V
		V _{GS} = 18V, I _D = 10A				
Static Drain - Source on - state resistance	R _{DS(on)} *5	T _j = 25°C	-	80	104	mΩ
		T _j = 150°C	-	136	-	
Gate input resistance	R_G	f = 1MHz, open drain	-	12	-	Ω

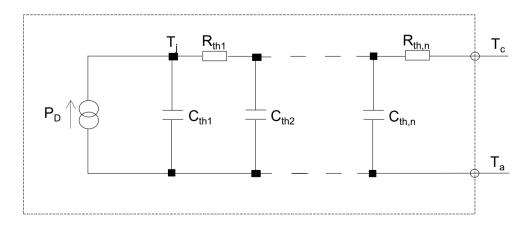
●Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R_{thJC}	-	0.70	0.91	°C/W

● Typical Transient Thermal Characteristics

Symbol	Value	Unit
R _{th1}	8.52×10 ⁻²	
R _{th2}	4.15×10 ⁻¹	K/W
R _{th3}	2.06×10 ⁻¹	

Symbol	Value	Unit
C_{th1}	1.22×10 ⁻³	
C_{th2}	6.20×10 ⁻³	Ws/K
C _{th3}	3.49×10 ⁻²	



●Electrical characteristics (T_a = 25°C)

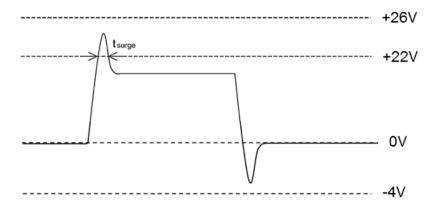
Dorometer	Cymbol	Conditions		Values		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Transconductance	g fs *5	$V_{DS} = 10V, I_{D} = 10A$	-	4.4	-	S
Input capacitance	C _{iss}	V _{GS} = 0V	-	785	ı	
Output capacitance	C _{oss}	V _{DS} = 800V	-	75	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	35	-	
Effective output capacitance, energy related	C _{o(er)}	$V_{GS} = 0V$ $V_{DS} = 0V \text{ to } 600V$	-	74	1	pF
Total Gate charge	Qg *5	$V_{DS} = 600V$ $I_{D} = 10A$	-	60	ı	
Gate - Source charge	Q _{gs} *5	$V_{GS} = 18V$	-	11	ı	nC
Gate - Drain charge	Q _{gd} *5	See Fig. 1-1.	-	31	-	
Turn - on delay time	t _{d(on)} *5	$V_{DS} = 600V$ $I_{D} = 10A$	-	5	1	
Rise time	t _r *5	$V_{GS} = 0V/+18V$	-	13	-	no
Turn - off delay time	t _{d(off)} *5	$R_G = 0\Omega, L = 750\mu H$ $L_{\sigma} = 50 nH, C_{\sigma} = 10 pF$	-	20	ı	ns
Fall time	t _f *5	See Fig. 2-1, 2-2, 2-3.	-	12	-	
Turn - on switching loss	E _{on} *5	E _{on} includes diode reverse recovery.	-	149	-	u l
Turn - off switching loss	E _{off} *5		-	12	-	μJ

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions		Values	Unit	
- Farameter	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Body diode continuous, forward current	I _S *1	T _c = 25°C	ı	ı	31	А
Body diode direct current, pulsed	I _{SM} *2	11 _c - 23 C	ı	ı	77	Α
Forward voltage	V _{SD} *5	$V_{GS} = 0V, I_{D} = 10A$	ı	3.2		V
Reverse recovery time	t _{rr} *5	$I_F = 10A$ $V_R = 600V$	ı	17	ı	ns
Reverse recovery charge	Q _{rr} *5	di/dt = 2500A/µs	1	261	ı	nC
Peak reverse recovery current	I _{rrm} *5	L_{σ} = 50nH, C_{σ} = 10pF See Fig. 3-1, 3-2.	-	26	ı	Α

^{*1} Limited by maximum temperature allowed.

*3 Example of acceptable V_{GS} waveform



Please note especially when using driver source that $V_{\text{GSS_surge}}$ must be in the range of absolute maximum rating.

4/12

*5 Pulsed

^{*2} $P_W \le 10\mu s$, Duty cycle $\le 1\%$

^{*4} Please be advised not to use SiC-MOSFETs with V_{GS} below 13V as doing so may cause thermal runaway.

0

25

•Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

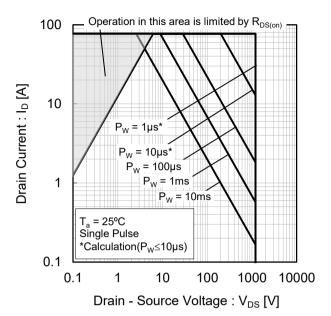


Fig.3 Typical Transient Thermal Resistance vs. Pulse Width

75

125

Case Temperature : T_C [°C]

175

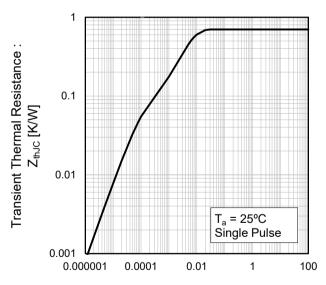


Fig.4 Typical Output Characteristics(I)

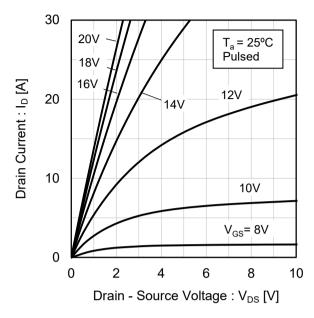


Fig.5 Typical Output Characteristics(II)

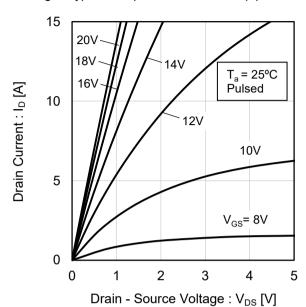
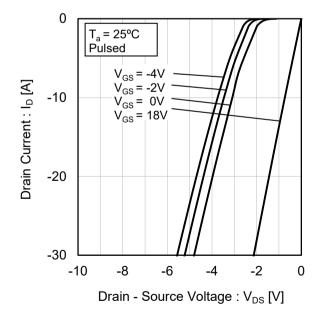
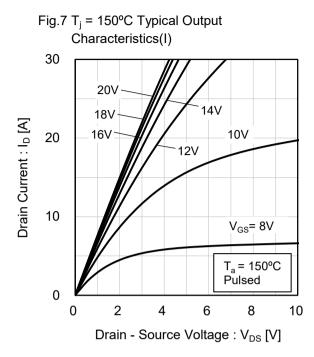


Fig.6 T_i = 25°C 3rd Quadrant Characteristics





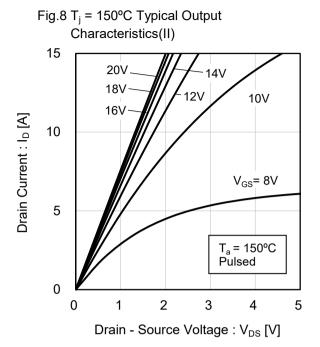


Fig.9 T_i = 150°C 3rd Quadrant Characteristics

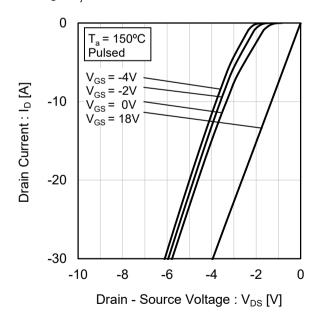


Fig.10 Body Diode Forward Voltage vs. Gate - Source Voltage

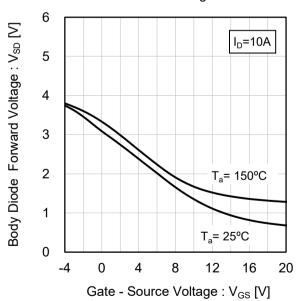


Fig.11 Typical Transfer Characteristics (I)

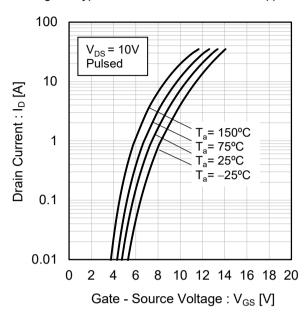


Fig.12 Typical Transfer Characteristics (II)

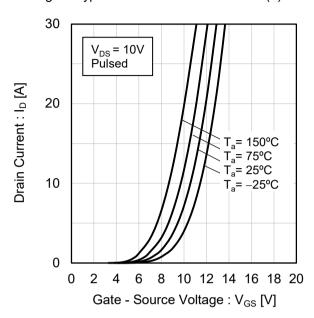


Fig.13 Gate Threshold Voltage vs. Junction Temperature

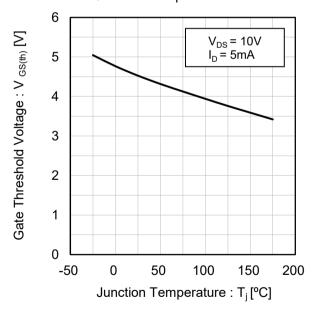
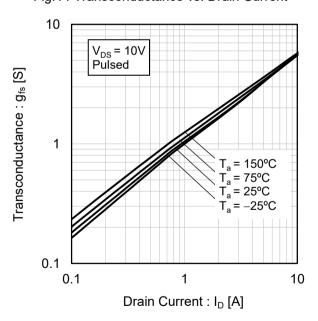
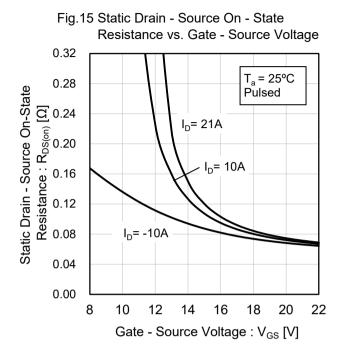


Fig.14 Transconductance vs. Drain Current





Resistance vs. Junction Temperature 0.18 $V_{GS} = 18V$ Static Drain - Source On-State Pulsed 0.15 I_D= 21A Resistance : $R_{DS(on)} [\Omega]$ I_D=10A 0.12 I_D= -10A 0.09 0.06 0.03 0.00 0 100 -50 50 150 200 Junction Temperature : T_i [°C]

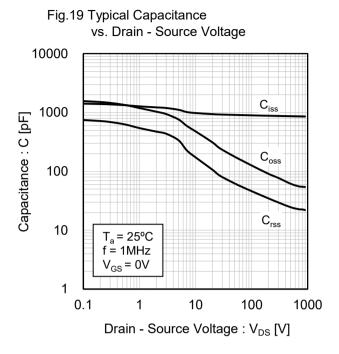
Fig.16 Static Drain - Source On - State

Fig.17 Static Drain - Source On - State Resistance vs. Drain Current 1 Static Drain - Source On-State Resistance : $R_{DS(on)} [\Omega]$ 0.1 T_a = 150°C = 125°C T_a = 75°C V_{GS} = 18V T_a = 25°C Pulsed $T_a = -25^{\circ}C$ 0.01 10 100 1 Drain Current: ID [A]

Voltage vs. Junction Temperature 1.04 1.03 Normalized Drain - Source Breakdown Voltage 1.02 1.01 1.00 0.99 0.98 -50 0 50 100 150 200 Junction Temperature : T_i [°C]

Fig.18 Normalized Drain - Source Breakdown





25
T_a = 25°C

T_a = 25°C

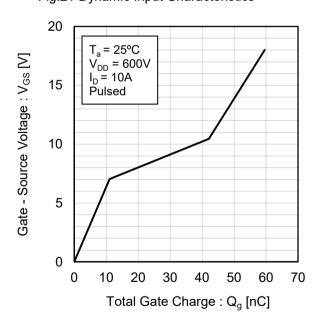
T_a = 25°C

10
0 100 200 300 400 500 600 700 800

Drain - Source Voltage : V_{DS} [V]

Fig.20 C_{oss} Stored Energy

Fig.21 Dynamic Input Characteristics



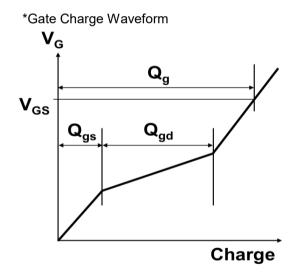


Fig.22 Typical Switching Time vs. External Gate Resistance

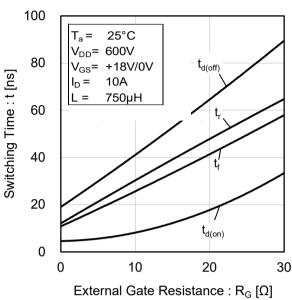


Fig.23 Typical Switching Loss vs. Drain - Source Voltage

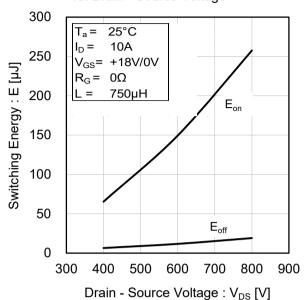


Fig.24 Typical Switching Loss vs. Drain Current

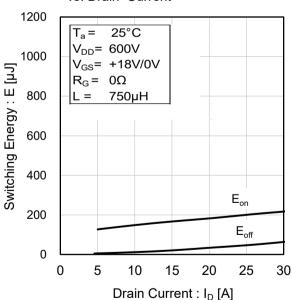
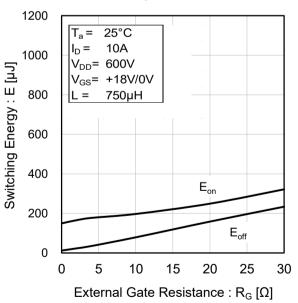


Fig.25 Typical Switching Loss vs. External Gate Resistance



Measurement circuits and waveforms

Fig.1-1 Gate Charge Measurement Circuit

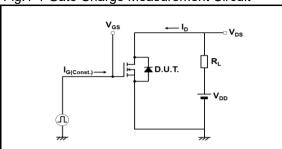


Fig.2-1 Switching Characteristics Measurement Circuit

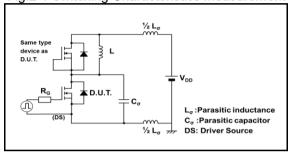


Fig.2-2 Waveforms for Switching Time

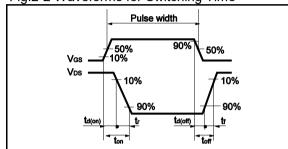


Fig.2-3 Waveforms for Switching Energy Loss

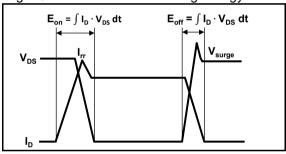


Fig.3-1 Reverse Recovery Time Measurement Circuit

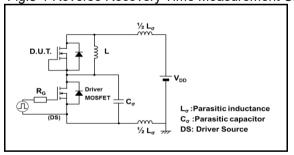
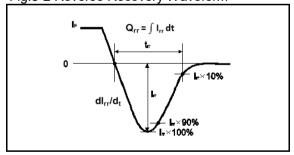


Fig.3-2 Reverse Recovery Waveform



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